

In re Divisional Patent Application of Basceri et al.
For: METHODS FOR FORMING AND INTEGRATED CIRCUIT
STRUCTURES CONTAINING ENHANCED-SURFACE-AREA CONDUCTIVE
LAYERS
Express Mail No. EL 874431013US
Express Mail Date: September 26, 2001

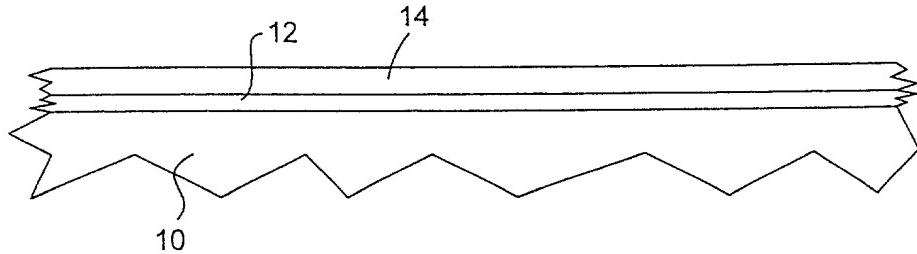


FIG. 1

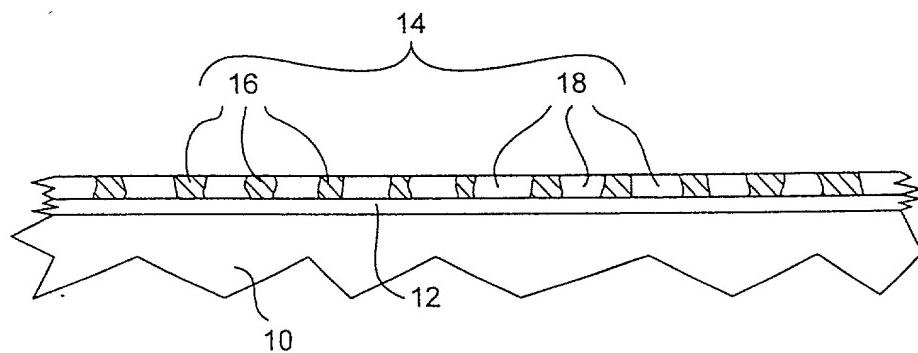


FIG. 2

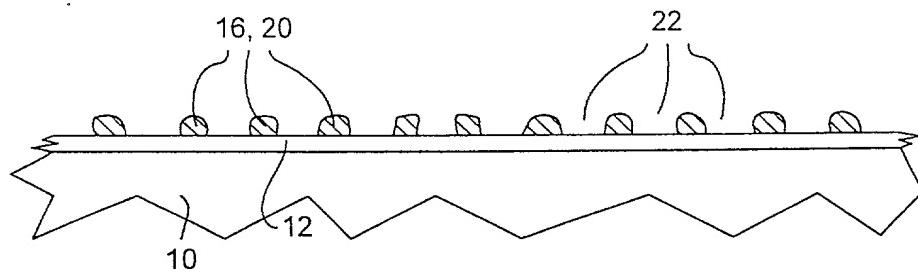


FIG. 3

09/655,609 10/23/01

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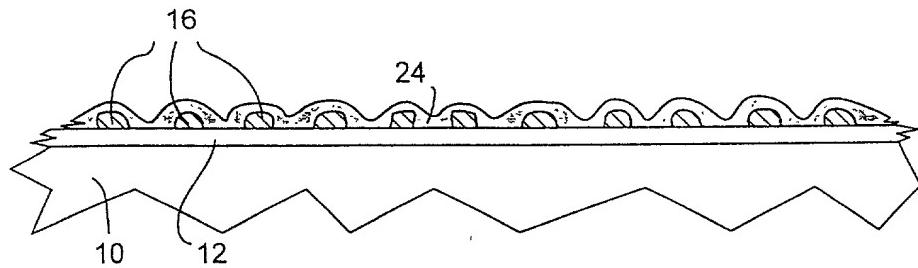


FIG. 4

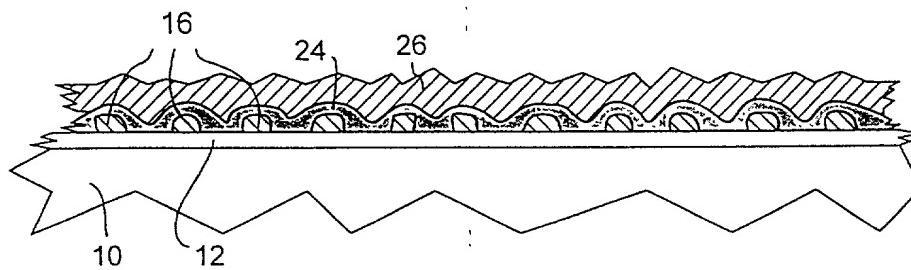


FIG. 5

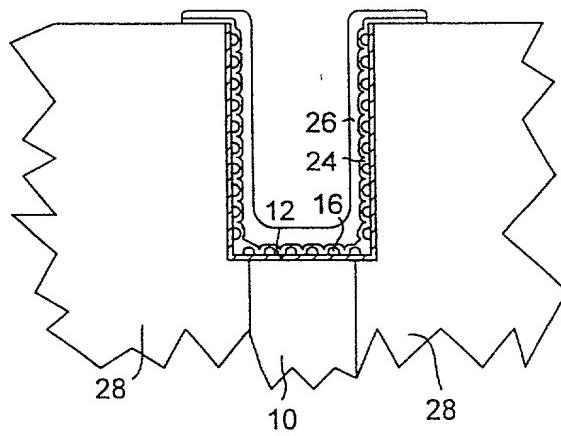


FIG. 6

FIG. 7

